



ESCC PROCESS CAPABILITY APPROVAL LIST (PCAL)

ESCC/RP/PCAL008-11

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| DCR No. | CHANGE DESCRIPTION |
|---------|---|
| 1536 | <p>New: 384, Kongsberg Space Electronics (Norway) Thin Film Hermetic Hybrid Microcircuits</p> <p>Extension: 346B, Safran Electronics (France)</p> |

FOREWORD

This document contains a list of suppliers of EEE manufacturing, assembly or test services that have been certified by the European Space Agency for Process Capability Approval (PCA) to the rules of the ESCC system with principal reference to ESCC Basic Specification no 25600.

The certification given to a supplier for Process Capability Approval does not include nor enable the ESCC Qualification of his products. Therefore, this listing of a PCA in this report just confirms the validity of the ESCC certification of approval within the limits of the applicable domain as described in a Process Identification Document (PID), but does not imply any declaration of individual product(s) qualification.

The electronic components produced within the domain described in the approved PID may need individual type (component) approval if intended for use in ESA and other spacecraft and associated equipment, in accordance with the requirements of the ECSS standard ECSS-Q-ST-60C.

Each PCA and its subsequent maintenance is monitored and overseen by the ESCC Executive. ESA certifies the PCA upon receipt of a formal recommendation raised by the ESCC Executive to state that all applicable ESCC requirements have been met by the pertinent manufacturer. The achieved PCA status is noted by an entry in this document, a corresponding entry in the European space components information exchange system, ESCIES, and the issue of a certificate to the certified manufacturer.

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1 PROMOTION

It is permitted to advertise the ESCC PCA status of a component supplier provided such publicity or advertisement does not state or imply that the related domain is the only approved one of that particular type, range or family.

2 PROCURER'S RESPONSIBILITY

When procuring EEE components produced within the limits of a certified PCA, the procurer is responsible for ensuring that the certification status is valid and that delivered components fulfil the specified contractual requirements in addition to those of the applicable ESCC specifications. The procurer is advised to utilise the ESCC non-conformance system, per ESCC Basic Specification No. [22800](#), in the event that a PCA-approved supplier delivers non-conforming components.

3 PCAL ORGANISATION**3.1 PROCESS CAPABILITY APPROVALS (PCA)**

The individual PCA are listed in this document by manufacturer in alphabetical order. They may also be found on the ESCIES web site, <https://escies.org>. A PCA Abstract is provided to describe the main features of the certified domain.

The individual PCA are listed in this document per PCA types: manufacturing line of Hermetic Hybrid Microcircuits according to ESCC2566000, manufacturing line of non-Hermetic microelectronic modules according to ESCC2566001 and hermetic assembly, packaging and test services from assembly and test houses (ATH) according to ESCC2567000 requirements.

3.2 MANUFACTURER

Contact information and plant locations are indicated in the individual PCA listings. Contact information may also be found in the ESCC PCAL section of the ESCIES web site, <https://escies.org>.

4 TABLE OF PROCESS CAPABILITY TECHNOLOGIES

| PCA Domain | Technology | Specification | Supplier | Cert. No. |
|---------------------|---|-----------------|-----------------------------------|-----------|
| Hermetic Hybrid | Thick Film Hermetic Hybrid Integrated Circuits and HTCC Hermetic Hybrid Integrated Circuits | ESCC 2566000 | Airbus Defense and Space, F | 345B |
| Hermetic Hybrid | Thick Film, Hermetic and HTCC Hermetic, low power, single cavity, Hybrids. | ESCC 2566000 | Safran Electronics and Defense, F | 346B |
| Hermetic Hybrid | Microwave Hybrid Integrated Circuits (MHIC) and High Density Integrated (HDI) RF Systems in Package (RF-SiP) using LTCC multilayer technology | ESCC 2566000 | Tesat Spacecom, G | 341C |
| Hermetic Hybrid | Low Frequency and Power Hybrid Line | ESCC 2566000 | Thales Alenia Space, B | 349A |
| Hermetic Hybrid | High Frequency Hybrid Line | ESCC 2566000 | Thales Alenia Space, F | 332C |
| Hermetic Hybrid | Hybrid Integrated Circuits (MHIC) product line and LTCC Integral Substrate Package (ISP) Hybrid Integrated Circuits | ESCC 2566000 | Thales Alenia Space, I | 343A |
| Hermetic Hybrid | Thin Film Hermetic Hybrid Microcircuits | ESCC 2566000 | Kongsberg Space Electronics, N | 384 |
| Non-hermetic Module | 3D Stacking Technology Modules | ESCC 2566001 | 3Dplus, F | 351B rev1 |
| ATH | Hermetically Encapsulated Discrete Semiconductor Components in SMD and TO Packages. | ESCC 2567000 | First Sensor Lewicki, G | 379 |

5 CERTIFIED PROCESS CAPABILITY APPROVALS

The following Process Capability Approvals are certified.

5.1 HERMETIC HYBRID LINES

5.1.1 AIRBUS DEFENCE & SPACE, FRANCE

The Process Capability Approval (PCA) of the Hybrid Line of Airbus Defence & Space in Elancourt, France, has been certified by ESA in accordance with the requirements of ESCC Basic specification No. [2566000](#).

The associated PID includes Airbus’ manufacturing, assembly and test operations which have been approved for the supply of Hermetic Hybrid products for use in ESA space systems as a Category1, Option 1 Manufacturer, in accordance with ECSS-Q-ST-60-05C Rev.1

5.1.1.1 Contact Information

| Address | ESCC Chief Inspector |
|--|---|
| Airbus Defence & Space 1, Boulevard Jean Moulin ZAC de la Clef Saint Pierre 78990 Elancourt, France | Mr. Dominique Mahasoro dominique.mahasoro@airbus.com |

5.1.1.2 Process Capability Approval

| Certificate No. | Certified since: | Type Designation |
|-----------------|------------------|--|
| 345B | Dec. 2016 | Thick Film Hermetic Hybrid Integrated Circuits and HTCC Hermetic Hybrid Integrated Circuits |

5.1.1.3 Capability Abstracts

5.1.1.3.1 Capability Abstract Thick Film Hybrids

The PCA associated to the PID GM.HYBR.NT.220.V.MMS Ed.21 Rev.00 covers the ADS-Elancourt activities on manufacturing, testing, inspection and Quality Assurance of Thick Film Hermetic Hybrid microcircuits used for Space application (internal ADS equipment and external customers). Electronic functions performed by thick film hybrids are digital, analog, 1553 Bus (couplers, transceivers), low frequency and low power.

ADS-Elancourt is category 1 hybrid manufacturer and applies Lot Acceptance Tests Option1 Production lot control according to the PID and as defined in ECSS-Q-ST-60-05C Rev.1.

- Active and passive chips (ASICs, Integrated circuits, Transistors, Diodes, Capacitors and Resistors) are adhesive attached on screen printed thick film alumina.
- Interconnections between dice and substrate are performed by ultrasonic wire bonding.

- Substrate is adhesive attached onto metal-based package.
- Interconnections between substrate and package are performed by thermosonic wire bonding.
- Metallic Flat Package (up to 40mm x 51mm) is hermetically sealed with lid under inert gas atmosphere.

The repair provisions (element replacement, wire re-bonding, delidding-relidding) are given in the PID.

Hybrid microcircuits are screened, according to the PID in conformance to the generic procurement specification ECSS-Q-ST-60-05C Rev.1. Manufacturing and screening operations are performed according to procedures listed in the PID.

The procurement of passive and active parts, materials and piece parts are performed according to procurement specifications and incoming procedures, as detailed in PID.

5.1.1.3.2 Capability Abstract HTCC Hybrids

The PCA associated to the PID GM.HYBR.NT.879.V.ASTR Ed.10 Rev.00 covers the ADS-Elancourt activities on manufacturing, testing, inspection and Quality Assurance of HTCC Hermetic Hybrid microcircuits used for Space application (internal ADS equipment and external customers). Electronic functions performed by HTCC hybrid microcircuits are digital, analog, 1553 Bus (couplers, transceivers), low frequency and low power.

ADS-Elancourt is a Category 1 hybrids manufacturer and applies Screening tests and Lot acceptance Tests Option1 Production lot control according to the PID and as defined in ECSS-QST-60-05C Rev.1.

- Active and passive chips (ASICs, Integrated circuits, Transistors, Diodes, Capacitors and Resistors) are adhesive attached onto Multilayer HTCC Aluminium Nitride package.
- Interconnections between dice and HTCC package are performed by ultrasonic wire bonding.
- Ceramic Flat package (up to 43mm x 30 mm) is hermetically sealed with lid under inert gas atmosphere.

The repair provisions (element replacement, wire re-bonding, delidding-relidding) are given in the PID.

Hybrid microcircuits are screened, according to the PID in conformance to the generic procurement specification ECSS-Q-ST-60-05C Rev.1. Manufacturing and screening operations are performed according to procedures listed in the PID.

The procurement of passive and active parts, materials and piece parts are performed according to procurement specifications and incoming procedures, as detailed in PID.

5.1.2 TESAT SPACECOM, GERMANY

The Process Capability Approval (PCA) of the Hybrid Line of Tesat Spacecom, Backnang, Germany, has been certified by ESA in accordance with the requirements of ESCC Basic specification No. [2566000](#).

The associated PID includes Tesat’s manufacturing, assembly and test operations which have been approved for the supply of Hermetic Hybrid products for use in ESA space systems as a Category1, Option 2 Manufacturer, in accordance with ECSS-Q-ST-60-05C Rev.1

5.1.2.1 *Contact Information*

| Address | ESCC Chief Inspector |
|---|------------------------|
| Tesat-Spacecom GmbH & Co. KG Gerberstraße 49 D-71522 Backnang Germany | Dr. – Ing. Jens Werner |

5.1.2.2 *Process Capability Approval*

| Certificate No. | Certified since: | Type Designation |
|-----------------|------------------|---|
| 341C | July 2016 | Microwave Hybrid Integrated Circuits (MHIC) and High Density Integrated (HDI) RF Systems in Package (RF-SiP) using LTCC multilayer technology |

5.1.2.3 *Capability Abstract*

TESAT’s microwave hybrid manufacturing line capabilities are defined within the associated Process Identification Document (PID) 63.0200.005.00PID, Issue K.

This PID describes hybrid assembly, packaging, production screening, test and quality assurance processes for Microwave Hybrid Integrated Circuits (MHIC) and for High Density Integrated (HDI) RF-Systems in Package (RF-SiP) using LTCC multilayer technology. The manufacturing and screening lines are highly automated and provide up to man-less 24/7 operation mode.

The TESAT buried microwave technology offers the highest possible degree of circuit integration at extreme electromagnetic shielding levels.

The packaging standard is hermetic sealing but non-hermetic packaging has also been evaluated. Sealed packages are metal-ceramic based and apply thin-film, or LTCC technology.

Such hybrids are applied in various TESAT space equipment like linearizers, channel amplifiers, frequency converters, low noise amplifiers, SSPAs, modulators, data link electronics, DC-controllers and optical communication systems (likely the hermetic variants) but also in commercial terrestrial applications (non-hermetic variants). The frequency range reaches up to V-band.

TESAT hybrids are suited for radar applications (T/R-modules, TRX-modules for satellite constellations or high throughput satellites) or SSPA building blocks for beam-forming antennas.

TESAT's microwave hybrid manufacturing services are offered in-house and also externally (<http://tesat.de/en/services/microwave-hybrid-manufacturing>).

All space modules are screened according to ECSS-Q-ST-60-05C including burn-in and life test monitoring

5.1.3 SAFRAN ELECTRONICS & DEFENSE, FRANCE

The Process Capability Approval (PCA) of the Hybrid Line of Safran Electronics & Defense in Valence, France, has been certified by ESA in accordance with the requirements of ESCC Basic specification No. [2566000](#).

The associated PID includes Safran Electronics & Defense’s manufacturing, assembly and test operations which have been approved for the supply of Hermetic Hybrid products for use in ESA space systems as a Category1, Option 1 Manufacturer, in accordance with ECSS-Q-ST-60-05C Rev.1

5.1.3.1 Contact Information

| Address | ESCC Chief Inspector |
|---|--|
| Safran Electronics & Defense 95 route de Montélier BP234 26002 VALENCE FRANCE | Mr. Stephane BLACHE stephane.blache@safrangroup.com |

5.1.3.2 Process Capability Approval

| Certificate No. | Certified since: | Type Designation |
|-----------------|------------------|---|
| 346B | Dec. 2016 | Thick Film, Hermetic and HTCC Hermetic, low power, single cavity, Hybrids |

5.1.3.3 Capability Abstract

SAFRAN ELECTRONICS & DEFENSE’s hybrid manufacturing line capabilities are defined within the associated Process Identification Document (PID) AQA 511 rev AB.

This PID describes hybrid assembly, packaging, production screening, test and quality assurance processes for Medium and Low power Hybrids Circuits using multilayer Thick film and HTCC (High Temperature Cofired Ceramics) technology.

Hybrids are used in equipment like power supplies, Video treatment, low noise amplifiers, data link electronics for telecom or scientific systems...

The hybrids are screened in house according to the PID. Regarding the Lot Acceptance Test SAFRAN ELECTRONICS & DEFENSE is compliant to Option 1 as default, but under customer agreement also the Option 2 can be applied (TRB, SPC, SEC).

According to the PID, the hybrids circuits are manufactured by encapsulation, of several types of active and passive components reported inside customized hermetic package: ASICs and digital/analog ICs, Transistors, Diodes, Capacitors, Resistors networks, Optocouplers, Magnetic devices, Thermistors ...

The choice, definition and procurement of active and passive chips, material and mechanical parts, the incoming inspection and the User-LAT test are performed according to custom specifications or PID procedures.

In-house process capabilities:

- Multilayer thick film printing
- Static and dynamic thick film resistors trimming.
- Single or double-sided hybrids
- Bare dices and SMT components: automatic pick-and-place assembly
- Automatic Wire bonding.
- Seam sealing
- Mix technologies on same hybrid circuit (HTCC+Thick film+Reflow soldering)
- Internal Expertise Laboratory: Destructive Physical Analysis (DPA), Elements characterizations, Failure analysis

Remark: Technologies and processes covering Rakon hybrid oscillator are currently not covered by the certified capability domain.

5.1.4 THALES ALENIA SPACE, BELGIUM

The Process Capability Approval (PCA) of the Hybrid Line of Thales Alenia Space (TAS), Charleroi, Belgium, has been certified by ESA in accordance with the requirements of ESCC Basic specification No. [2566000](#).

The associated PID includes TAS' production flow (manufacturing, assembly and test operations which has been approved for the supply of Hermetic Hybrid products for use in ESA space systems as a Category1, Option 1 Manufacturer, in accordance with ECSS-Q-ST-60-05C Rev.1

5.1.4.1 Contact Information

| Address | ESCC Chief Inspector |
|--|---|
| Thales Alenia Space Rue Chapelle Beaussart 101 B-6032 Mont-sur-Marchienne (Charleroi) Belgium | JD. Carton P. Deporte (deputy) Tel. +32 71 44 27 66 |

5.1.4.2 Process Capability Approval

| Certificate No. | Certified since: | Type Designation |
|-----------------|------------------|-------------------------------------|
| 349A | April 2018 | Low Frequency and Power Hybrid Line |

5.1.4.3 Capability Abstract

The associated Process Identification Document (PID) is referenced 9100.0683 Issue 8.2

The PCA covers the TAS-B activities in the field of manufacturing, testing, screening and Quality Assurance of Low-Frequency and Power Hermetic Hybrid technologies, produced to be embedded in modules assembled on TAS space equipment and sub-systems. TAS-B also delivers hybrids in direct to external customers (DC/DC converters...).

According to the PID, the hermetic modules are designed and manufactured for the integration of function as "thick film" MCMs. These hybrids integrate several types of active and passive add-on parts, inside customized hermetic package: analogic and digital ICs, ASICs, bare chips (transistors & diodes), Capacitors, Resistors, Inductors and transformers, Thermistors, Thin-Film and Thick-Film circuits. Various types of wires are used for interconnection on dies and substrates or package (Al, Au, Cu).

Various types of sealing are available to obtain a hermetic cavity under inert gas atmosphere. Depending of the application, the hermetic package is made of metal (Kovar or Aluminium) with glass or ceramic feedthroughs. The use of ceramic HTCC package is also part of the PCA.

At the final step of production, hybrid modules are screened, according to the PID and to the generic procurement specification ECSS-Q-ST-60-05C Rev. 1.

The repair provision conditions (element replacement, re-bonding, de-lidding ...), as well as the criteria for lot rejection are also given in the PID, in accordance with ECSS-Q-ST-60-05C Rev. 1.

The procurement of passive and active components, materials and mechanical parts are assured according to internal procurement specifications and incoming instructions, as detailed in PID. The associated internal tests namely include bondability, shear tests, and user-LAT carried out per ECSS-Q-ST-60-05C Rev. 1.

In matter of LAT, TAS-B validates the hybrid lots produced according to "Option 1" of ECSS-Q-ST60-05C Rev. 1.

5.1.5 THALES ALENIA SPACE, FRANCE

The Process Capability Approval (PCA) of the Hybrid Line of Thales Alenia Space (TAS), Toulouse, France has been certified by ESA in accordance with the requirements of ESCC Basic specification No. [2566000](#).

The associated PID includes TAS' manufacturing, assembly and test operations which have been approved for the supply of Hermetic Hybrid products for use in ESA space systems as a Category1, Option 2 Manufacturer, in accordance with ECSS-Q-ST-60-05C Rev.1

5.1.5.1 Contact Information

| Address | ESCC Chief Inspector |
|---|---|
| Thales Alenia Space 26, Av. J.-F. Champollion BP33787 31037 Toulouse Cedex 1 France | Mr. Roland Queriaud Tel. +33 5 3435 6338 |

5.1.5.2 Process Capability Approval

| Certificate No. | Certified since: | Type Designation |
|-----------------|------------------|----------------------------|
| 332C | May 2015 | High Frequency Hybrid Line |

5.1.5.3 Capability Abstract

The Process Capability Approval (PCA) of the Hybrid Line of Thales Alenia Space (Toulouse) has been renewed in accordance with ESCC Basic Specification n° 2566000 requirements. The associated Process Identification Document (PID) is Ref. 39.731.284/924, Issue 11/-.

This PCA covers the TAS-Toulouse activities on manufacturing, tuning, testing, inspection and Quality Assurance of High-Frequency Hermetic Hybrid technologies, used for high power and low power modules of TAS space equipment and sub-systems.

According to the PID, the hermetic modules are manufactured by encapsulation, of several types of active and passive components, inside customized hermetic package:

- MMICs,
- ASICs and digital/analog ICs
- Bare transistors,
- Diodes,
- Capacitors,
- Resistors,
- Inductors and transformers,
- Thermistors.
- Thin-Film and Thick-Film circuits

Wires and ribbons are used for interconnection between the dies, and between dies and substrates or package.

Hermetic cavities are generated with lid sealing under inert gas atmosphere.

Depending of the application, the hermetic package is metal-based or HTCC-based, with glass or ceramic for DC or RF feedthroughs.

Then, modules are screened, according to the PID and to the generic procurement specification ECSS-Q-ST-60-05C Rev. 1.

The repair provision conditions (element replacement, re-bonding, delidding ...), as well as the criteria for lot rejection are also given in the PID, in accordance with ECSS-Q-ST-6005C Rev. 1.

Procurements of passive and active components, materials and mechanical parts are performed following internal procurement specifications and incoming instructions, as detailed in PID. The associated internal tests include bond ability tests as well as user-LAT tests, as required by ECSS-QST-60-05C Rev. 1.

For Hybrid Circuit Lot Acceptance Test (Hybrid LAT), TAS-Toulouse follows "Option 2", as defined in ECSS-Q-ST-60-05C Rev. 1.

For this purpose, TAS-Toulouse has defined, for the Manufacturing Hybrid Line:

- The generalization of Statistical Process Control of the manufacturing means,
- The implementation of a Hybrid Line Management under the control of a Technology Review board (TRB). Organization, missions and responsibilities of this TRB is defined in an internal TAS instruction.
- The implementation of Standard Evaluation Circuits (SECs), used for LAT acceptance. Several different SECs are requested to cover the whole range of hybrid technologies. These SECs are Flight Model Hybrids, sampled, and submitted to destructive acceptance tests, in accordance to PID and ECSS-Q-ST-60-05C Rev. 1.

5.1.6 THALES ALENIA SPACE, ITALY

The Process Capability Approval (PCA) of the Hybrid Line of Thales Alenia Space (TAS), L'Aquila, Italy, has been certified by ESA in accordance with the requirements of ESCC Basic specification No. 2566000.

The associated PID includes TAS' manufacturing, assembly and test operations which have been approved for the supply of Hermetic Hybrid products for use in ESA space systems as a Category1, Option 2 Manufacturer, in accordance with ECSS-Q-ST-60-05C Rev.1

5.1.6.1 *Contact Information*

| Address | ESCC Chief Inspector |
|---|---|
| Thales Alenia Space Zona Industriale Frazione di Pile (snc), 67100 L'Aquila Italy | Mr. F. Vasarelli Tel. +39 0862 707 313 |

5.1.6.2 *Process Capability Approval*

| Certificate No. | Certified since: | Type Designation |
|-----------------|------------------|---|
| 343A | October 2016 | Hybrid Integrated Circuits (MHIC) product line and LTCC Integral Substrate Package (ISP) Hybrid Integrated Circuits |

5.1.6.3 *Capability Abstract*

The PID PCP-14-60-013 Iss.F covers the TAS-I L'Aquila activities on manufacturing, tuning, testing, inspection and quality assurance of Microwave Hybrid Integrated Circuits (MHIC's) and LTCC Integral Substrate Package (I.S.P.) Hybrid Integrated Circuits, installed on space Units Hardware for TAS Equipment, Sub-System and Antennas.

The MHICs manufactured in L'Aquila have customized packages and they can be made by means different technologies, according specific need and performances, as mechanical housing with brazed glass or ceramic feed-through or connectors or as Integral Substrate Package (ISP) based on Low Temperature Ceramic Cofired (LTCC) or High Temperature Ceramic Cofired (HTCC).

The MHICs housing can be populated by Thin Film Al2O3 or LTCC or Thick Film on multilayer Al2O3 (Ref. proper PID 14-40-001) ceramic substrates, manufactured, on a dedicated line in TAS-I L'Aquila as reported in the PID, glued or brazed on the MHIC housing.

The MHICs are populated with a lot of active and passive components selected to meet specific functions and performances : MMICs , ASICs, SRAMs, Digital Analog and RF ICs, Transistors, Diodes, Capacitors, Resistors, Inductors, Circulators and Thermistors. These components are mounted on the substrates by dispensing of different epoxy adhesive or by brazing process.

The interconnections among parts and substrates are made by wiring or ribbons in different materials and size and using different techniques.

The thermal dissipation for the most critical devices is managed by the use of heat spreader glued with high thermal conductive adhesive or brazed onto metal carrier.

Hermetic cavity is generated by lid sealing process, Seam or Laser Welding techniques, in inert gas atmosphere.

The procurement of active and passive chips, material and mechanical parts , the incoming inspection and the User-LAT test are performed according to dedicated procurement specifications or procedures reported in the PID and in conformance to ECSS-Q-ST-60-05C.

The MHICs are screened in house according to the PID and in conformance to ECSS-Q-ST-60-05C, as well the rework provisions and the Lot Acceptance Criteria. Regarding the MHIC Lot Acceptance Test TAS-I L'Aquila is compliant to Option 2 as default, but under customer agreement also the Option 1 can be applied. In addition for the Option 2 TAS-I L'Aquila defined a Technology Review Board (TRB) which supervises the Statistical Process Control (SPC) on manufacturing line processes, and implemented Standard Evaluation Circuit (SEC) policy for LAT acceptance. The SECs, coming from different Flight Model and taken from the manufacturing line, are able to cover the whole MHIC Technology Domain, and they are submitted to Destructive Physical Analysis (DPA) according to PID and ECSS-Q-ST-60-05C.

5.1.7 KONGSBERG SPACE ELECTRONICS (KSE), NORWAY

The Process Capability Approval (PCA) of the Hybrid Line of Kongsberg, Horten, Norway, has been certified by ESA in accordance with the requirements of ESCC Basic specification No. [2566000](#).

The associated PID includes Kongsberg’s manufacturing, assembly and test operations which have been approved for the supply of Hermetic Hybrid products for use in ESA space systems as a Category1, Option 2 Manufacturer, in accordance with ECSS-Q-ST-60-05C Rev.1

5.1.7.1 *Contact Information*

| Address | ESCC Chief Inspector |
|---|--|
| Kongsberg Space Electronics Knudsrødveien 7 N-3189 Horten Norway | Rolf Johannessen Rolf.Johannessen@kongsberg.com |

5.1.7.2 *Process Capability Approval*

| Certificate No. | Certified since: | Type Designation |
|-----------------|------------------|---|
| 384 | Nov 2022 | Thin Film Hermetic Hybrid Microcircuits |

5.1.7.3 *Capability Abstract*

Kongsberg Space Electronics (KSE) hybrid manufacturing process capabilities are defined within the associated Process Identification Document (PID) NORS\HYBRID\GEN\MIF\PID1198.

The process capability domain associated to the PID covers the KSE activities on design, manufacturing, testing, inspection, screening and quality assurance processes for thin film hybrid microcircuits used for space applications. Both medium and low power, RF and DC hybrid microcircuits are designed and manufactured.

The use can be on internal KSE equipment or sold to external customers.

The hybrids are manufactured by attaching active and passive components on thin film substrates, on metal carriers or directly into the package base, by conductive epoxy adhesives or by eutectic soldering:

- MMICs
- Digital/analog ICs
- Transistors
- Diodes
- Capacitors
- Resistors
- Inductors and transformers

- Thermistors
- Thin-Film circuits

Internal interconnections are performed by thermosonic bonding of wires or ribbons or by parallel gap welding. Hermeticity is achieved by resistive seam sealing under Nitrogen atmosphere. The packages are custom designed metallic or ceramic flat packages with a kovar seal ring and fitted with a kovar lid. The feed throughs may be glass or ceramic or of GPO/MDM type.

The repair provisions (element replacement, wire re-bonding, delidding-relidding) are given in the PID.

Hybrid microcircuits are screened, according to the PID in accordance with the requirements of ESCC Basic specification No. [2566000](#). The procurement of passive and active parts, materials and piece parts are performed according to procurement specifications and incoming procedures, as detailed in PID.

In-house process capabilities:

- Thin film substrate patterning
- Static and dynamic thin film resistors trimming
- Manual and automatic pick-and-place assembly
- Manual and automatic wire bonding
- Seam sealing
- Internal Expertise Laboratory: Destructive Physical Analysis (DPA), Elements characterizations, Failure analysis.

5.2 NON-HERMETIC MODULES LINES

5.2.1 3D PLUS, FRANCE

The Process Capability Approval (PCA) of the Production and Test Line of 3D PLUS in Buc, France, has been certified by ESA in accordance with the requirements of ESCC Basic specification No. [2566001](#).

The associated PID No. 3300-0546 issue 13 includes 3D PLUS' manufacturing, assembly and test operations which have been approved for the supply of non-hermetic modules for use in ESA space systems.

5.2.1.1 *Contact Information*

| Address | ESCC Chief Inspector |
|--|--|
| 3D plus 408, rue Hélène Boucher – Z.I. 78532 BUC Cedex France | Mr. Loïc LE ROY loic.le.roy@3d-plus.com |

5.2.1.2 *Process Capability Approval*

| Certificate No. | Certified since: | Type Designation |
|-----------------|------------------|--------------------------------|
| 351B rev1 | Nov. 2017 | 3D Stacking Technology Modules |

5.2.1.3 *Capability Abstract*

The associated Process Identification Document (PID) is Ref. 3300-0546-13 (PID Rev.13) and Ref. 3320-0150-1 (Amdt 1).

Since the Rev.11 of the PID, ESCC N°2566001 standard is the reference for the definition and evolution of the Process Capability Approval (PCA). This PCA covers the 3D PLUS Buc activities on manufacturing, tuning, testing, inspection and Quality Assurance of 3D stacked products used for 3D PLUS catalogue and custom products.

According to the PID, the 3D PLUS modules are manufactured by stacking several layers of active and passive components. Two manufacturing flows are defined as follows:

- Flow 1 for the stacking of memories with TSOP packages.
- Flow 2 for the stacking of thin PCBs (Flex) populated with EEE components. These components are assembled by soldering when used in packages or by wire bonding when used in dice form.

Flow 2 allows a large diversity of packages (TSOP, PQFP, FBGA...) enabling the design and manufacturing of complex products.

Then, modules are screened, according to the PID, and to the generic procurement specification ECSS-Q-ST-60-05C.

The repair provision conditions as well as the criteria for lot rejection are also given in the PID.

The procurement of passive and active components, materials and mechanical parts are performed following internal procurement specifications and incoming instructions, as detailed in PID. Commercial EEE Active components

Evaluation is in conformance with ECSS-Q-ST-60-13C standard.

For Module Lot Acceptance Test (Module LAT), 3D PLUS follows the ECSS-Q-ST-60-05C adapted to non-hermetic and cavity free modules.

5.3 ASSEMBLY AND TEST HOUSES (ATH)

5.3.1 FIRST SENSOR LEWICKI, GERMANY

The Process Capability Approval (PCA) of ATH services from First Sensor Lewicki in Oberdischingen, Germany, has been certified by ESA in accordance with the requirements of ESCC Basic specification No. [2567000](#).

5.3.1.1 *Contact Information*

| Address | ESCC Chief Inspector |
|--|--|
| First Sensor Lewicki GmbH Allee 35 89610 Oberdischingen, Germany | Mr. Jürgen Däubler juergen.daeubler@te.com |

5.3.1.2 *Process Capability Approval*

| Certificate No. | Certified since: | Type Designation |
|-----------------|------------------|--|
| 379 | March 2022 | Hermetically Encapsulated Discrete Semiconductor Components in SMD and TO Packages |

5.3.1.3 *Capability Abstract ATH service for hermetic discrete components*

First Sensor Lewicki’s assembly and test capabilities are defined within the associated Process Identification Document (PID) FSL797000-002 PID Issue B.

This PID describes discrete components assembly, packaging, screening, test and quality assurance processes for hermetic encapsulated power MOSFETs in SMD and TO packages.

Hermetic power MOSFETs form a key component in many applications such as general power supply of systems and sub-systems, DC-DC converter, motor control. The power MOSFETs are screened and tested in house according to the PID and are fully compliant with the ESCC5000.

The choice, definition and procurement of chips and packages, the incoming inspection and LAT test are performed according to custom specifications or PID procedures.

In-house process capabilities:

- Bare dices components: automatic pick-and-place assembly
- Solder die attach
- Automatic wire bonding
- Parallel seam sealing (for SMD and rectangular TO packages)
- Projection welding (for circular TO packages)

Screening of n-channel power MOSFETs according to ESCC5000 including environmental and mechanical tests, electrical tests, endurance tests and assembly tests.